



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-10
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
BAS70-04WFILM	HJUE*NHBAR28	A	Z55A	2016-06-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	6.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Alloy 42		

Package Designator	Size	Nbr of instances	Shape	
DSO	2 - 1.26 - 0.93	3	gull wing	
Comment	Package: SOT 323 SERIE 3L			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HJUE*NHBAR28					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.101	mg	supplier	die	Silicon (Si)	7440-21-3		0.088	mg	871287	14667
				supplier	metallization	Aluminium (Al)	7429-90-5		0.012	mg	118812	2000
				supplier	Passivation	Silicon Oxide	7631-86-9		0.001	mg	9901	167
Leadframe	Other Ferrous alloys, non-stainless ste	1.678	mg	supplier	alloy	Iron (Fe)	7439-89-6		0.933	mg	556019	155500
				supplier	alloy	Nickel (Ni)	7440-02-0		0.664	mg	395709	110667
				supplier	alloy	Manganese (Mn)	7439-96-5		0.010	mg	5959	1667
				supplier	alloy	Cobalt (Co)	7440-48-4		0.008	mg	4768	1333
				supplier	alloy	Silicon (Si)	7440-21-3		0.002	mg	1192	333
Bonding wire	Precious metals	0.024	mg	supplier	metallization	Silver (Ag)	7440-22-4		0.061	mg	36353	10167
				supplier	wire	Gold (Au)	7440-57-5		0.024	mg	1000000	4000
				supplier	mold compound	SiO2	60676-86-0		3.470	mg	872517	578333
Encapsulation	Other organic materials	3.977	mg	supplier	mold compound	Epoxy Resin	29690-82-2		0.200	mg	50289	33333
				supplier	mold compound	Phenol Resin	26834-02-6		0.200	mg	50289	33333
				supplier	mold compound	Aromatic poly-phosphate	proprietary		0.099	mg	24893	16500
				supplier	mold compound	Carbon Black	1333-86-4		0.008	mg	2012	1333
Connections coating	Solder	0.220	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.220	mg	1000000	36667